

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/05/2022

Details for "OPA4340EA/250G4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
OPA4340EA/250G4	NIPDAU	Level-2-260C-1 YEAR	TI MALAYSIA A/T	DBQ 16	5,0x4,0x1,75	83.5

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.067889	99.998527	999985	0.081347	813
Precious Metals	Silver	7440-22-4	0.000001	0.001473	15	0.000001	0
Sub-Total			0.06789	100	1000000	0.081348	813
Die Attach Adhesive							
Other Inorganic Materials	Silica	7631-86-9	0.017063	1.999979	20000	0.020446	204
Precious Metals	Silver	7440-22-4	0.58868	69.000034	690000	0.705378	7054
Thermoplastics	Epoxy	85954-11-6	0.247416	28.999987	290000	0.296463	2965
Sub-Total			0.853159	100	1000000	1.022286	10223
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	30.95815	99.865	998650	37.095194	370952
Copper and Its Alloys	Iron	7439-89-6	0.031	0.1	1000	0.037145	371
Copper and Its Alloys	Phosphorus	7723-14-0	0.01085	0.035	350	0.013001	130
Sub-Total			31	100	1000000	37.14534	371453
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.456576	95.12	951200	0.547086	5471
Precious Metals	Gold	7440-57-5	0.003744	0.78	7800	0.004486	45
Precious Metals	Palladium	7440-05-3	0.01968	4.1	41000	0.023581	236
Sub-Total			0.48	100	1000000	0.575154	5752
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	41.50587	85.999999	860000	49.73386	497339
Other Plastics and Rubber	Carbon Black	1333-86-4	0.144788	0.3	3000	0.17349	1735
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.265445	0.550001	5500	0.318066	3181
Thermoplastics	Epoxy	85954-11-6	6.346537	13.15	131500	7.604654	76047
Sub-Total			48.26264	100	1000000	57.830071	578301
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.79227	100	1000000	3.345801	33458
Sub-Total			2.79227	100	1000000	3.345801	33458
Total			83.455959			100	1000000

Important Note
 The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSi or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer
 TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
 Created on: 06/05/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J57098 low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.